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Part Number:

0737801147

Status:

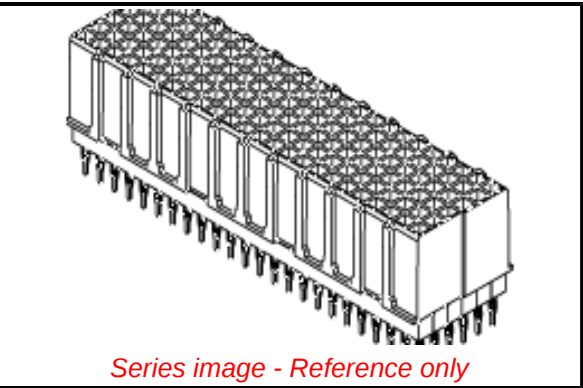
Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 17.00mm, Pin Length 3.00mm, Solder Tail



Documents:

Drawing (PDF)

Product Specification PS-73780-999-001 (PDF)

Packaging Specification PK-70873-0872 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification	
UL	E29179
General	
Product Family	Backplane Connectors
Series	73780
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754870665
Physical	
Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	20.030/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.00mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole
Electrical	

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Not Contained Per -

ED/61/2018 (27 June

2018)

Halogen-Free

Status

Low-Halogen

Need more information on product

environmental compliance?

Email productcompliance@molex.com

Please visit the [Contact Us](#) section for any

non-product compliance questions.

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

73780 Series

Mates With

HDM Board-to-Board Backplane Header

73642 , 73643 , 73644 , 73942 , 73943 ,

73944 , 7 4349, 74428. HDM Board-to-

Board Stacking Header 73769 , 73770 ,

73782 , 73783 , 73771

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-freeProcess Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0872
Product Specification	PS-73780-999-001
Sales Drawing	SD-73780-004

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